Product Change Notification

108260 - 00

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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Product Change Notification

Change Notification #:	**108260 - 00**
Change Title:	**Intel Carrier Grade Server TIGW1U, PCN 108260-00, Product Design, Changed sheet metal to enhance rack mount options, GCM port, captive screw, and insulator, drive bay, and fan bracket.**
Date of Publication:	**February 26, 2008**

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Mar 31, 2008

Description of Change to the Customer:

1. Changed base chassis to enable use of AXXBASICRAIL, AXXBASRAIL13, or AXXHERAIL (in non-NEBS environment). Change added:
    a. Two new positions (A in figure 1 below) per side to add 4 Hex Shoulder Screws.
    b. Additional position (C and D in figure 1 below) for attaching rail and mounting ear.

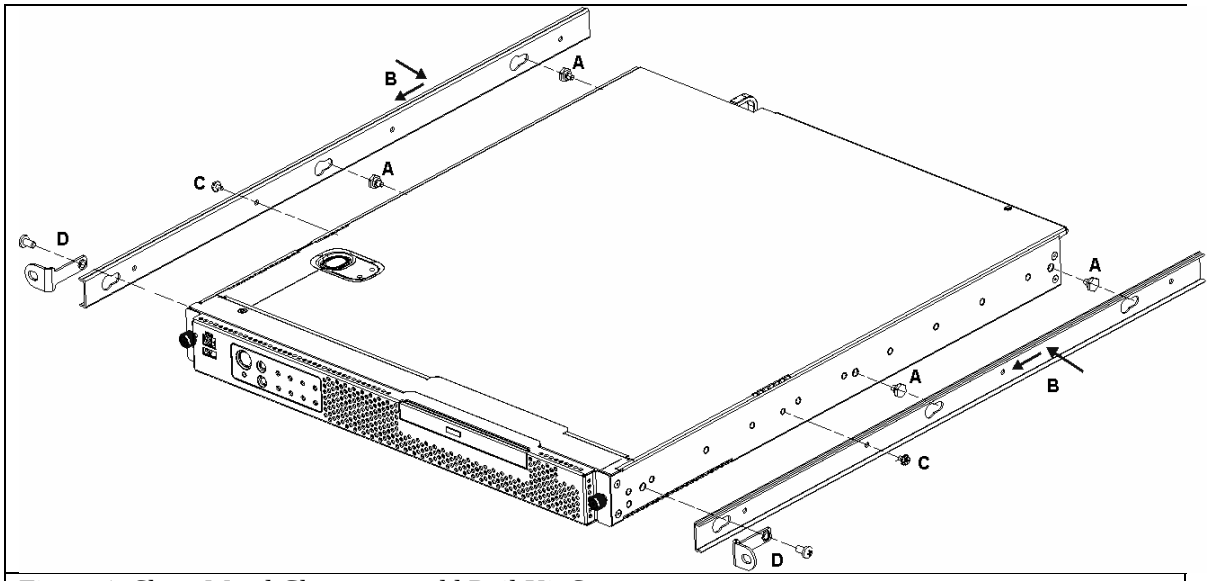

Figure 1. Sheet Metal Changes to add Rail Kit Support

2. Changed GCM NIC port to add notch for better clearance when module is installed.

Figure 2. GCM NIC port sheet metal change.

3. Changed Captive Screw type on PCI riser, as shown in Figure 3.

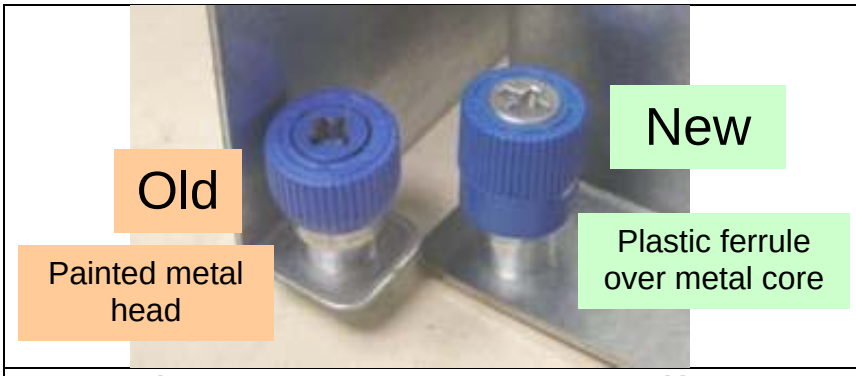

Figure 3. Change to Captive Screw on PCI riser assembly

4. Changed insulator material between boards and chassis, and on PCI support bracket from Formex* to Statex*. Added additional adhesive to improve adhesion at higher temperature.

5. Added clips to the drive bay to reduce transmission of rotational vibration, as shown in Figure 4.

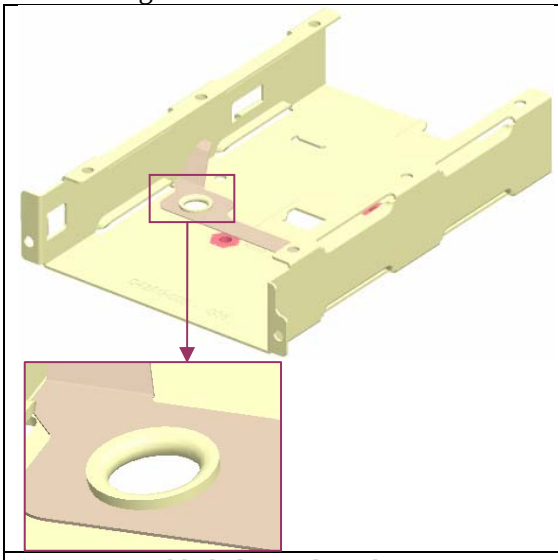

Figure 4. Added clip to drive bay

6. Changed CPU Fan Bracket sheet metal to improve RV (Rotational Vibration) performance.
    a. #1. Re-located rivet holes on outside surface to eliminate the gap/twist problem.
    b. Deleted two bay dividers (#2), leaving one divider for better RV performance.

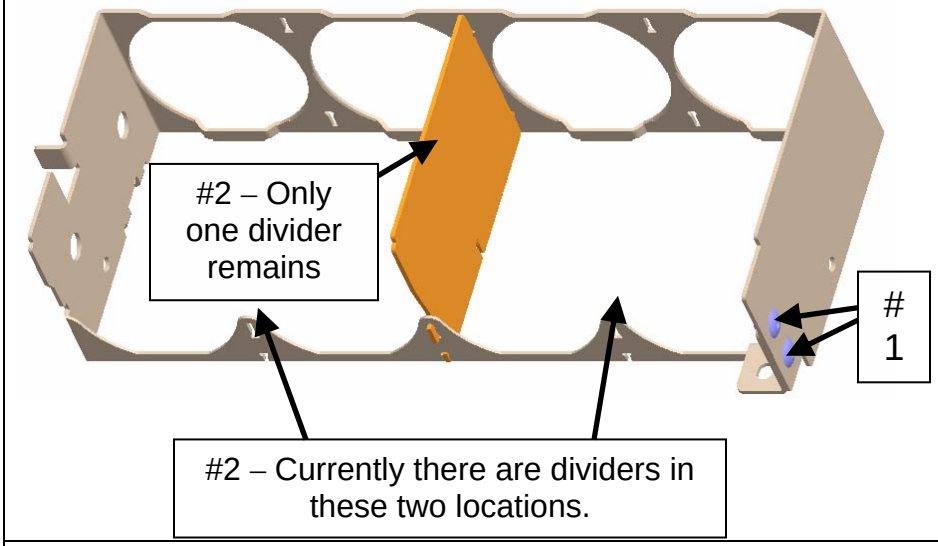

Figure 5. Changed Fan Bracket Sheet Metal.

Customer Impact of Change and Recommended Action:

These changes have been tested and passed a validation cycle on the Intel® Carrier Grade Server TIGW1U.

1. Customer should evaluate additional rack mount options.

2. Additional ease of assembly when using GCM port.

3. No impact.

4. Customer should appreciate better adhesion.

5. Change made to reduce transmission of rotational vibration.

6. Change made to reduce transmission of rotational vibration.

Products Affected / Intel Ordering Codes:

Pre Change Product Code	Pre Change MM#	Pre Change TA	Post Change TA
TMWD0201W	885430	D74315-010	D74315-011
TMWA0201W	885431	D74314-010	D74314-011

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
February 26, 2008	00	Originally Published PCN